TPD3E001
LOW-CAPACITANCE 3-CHANNEL ±15-kV ESD-PROTECTION ARRAY FOR HIGH-SPEED DATA INTERFACES

SLLS683D – JULY 2006 – REVISED APRIL 2007

FEATURES

- **ESD Protection Exceeds**
  - **±15-kV Human-Body Model (HBM)**
  - **±8-kV IEC 61000-4-2 Contact Discharge**
  - **±15-kV IEC 61000-4-2 Air-Gap Discharge**
- **Low 1.5-pF Input Capacitance**
- **Low 1-nA (Max) Leakage Current**
- **Low 1-nA Supply Current**
- **0.9-V to 5.5-V Supply-Voltage Range**
- **3-Channel Device**
- **Space-Saving DRL, DRY, and QFN Package Options**
- **Alternate 2-, 4-, and 6-Channel Options Available: TPD2E001, TPD4E001, and TPD6E001**

APPLICATIONS

- **USB 2.0**
- **Ethernet**
- **FireWire™**
- **Video**
- **Cell Phones**
- **SVGA Video Connections**
- **Glucosemeters**

DESCRIPTION/ORDERING INFORMATION

The TPD3E001 is a low-capacitance ±15-kV ESD-protection diode array designed to protect sensitive electronics attached to communication lines. Each channel consists of a pair of diodes that steer ESD current pulses to V_{CC} or GND. The TPD3E001 protects against ESD pulses up to ±15-kV Human-Body Model (HBM), ±8-kV Contact Discharge, and ±15-kV Air-Gap Discharge, as specified in IEC 61000-4-2. This device has a 1.5-pF capacitance per channel, making it ideal for use in high-speed data IO interfaces.

The TPD3E001 is a triple-ESD structure designed for USB On-the-Go (OTG) and video applications.

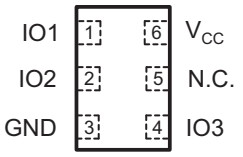
The TPD3E001 is available in DRL, DRY, and thin QFN packages and is specified for –40°C to 85°C operation.

ORDERING INFORMATION

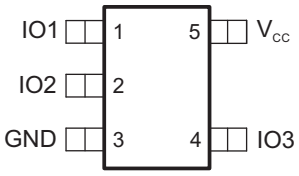
T_A	PACKAGE(1)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	1.6 × 1.6 SOP – DRL	TPD3E001DRLR	2BR
	1.45 × 1 SON – DRY	TPD3E001DRYR	2B
	3 × 3 QFN – DRS	TPD3E001DRSR	ZWL

(1) For the most current package and ordering information, see the Package Option Addendum at the end of this document, or see the TI website at www.ti.com.

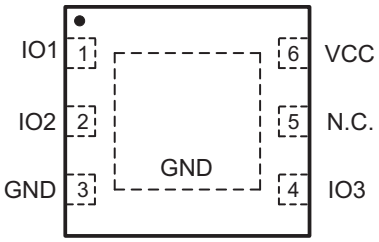
DRY PACKAGE (TOP VIEW)



DRL PACKAGE (TOP VIEW)

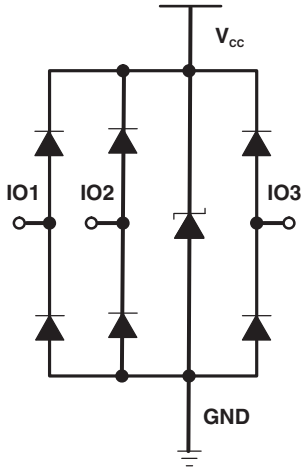


QFN PACKAGE (TOP VIEW)



N.C. - Not internally connected

LOGIC BLOCK DIAGRAM



PIN DESCRIPTION

DRL NO.	DRY NO.	DRS NO.	NAME	FUNCTION
1, 2, 4	1, 2, 4	1, 2, 4	IOx	ESD-protected channel
3	3	3	GND	Ground
5	6	6	V_{CC}	Power-supply input. Bypass V_{CC} to GND with a 0.1-µF ceramic capacitor.
	5	5	N.C.	No connection. Not internally connected.
		EP	EP	Exposed pad. Connect to GND.

Absolute Maximum Ratings(1)

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
V_{CC}			–0.3	7	V
$V_{I/O}$			–0.3	V_{CC} + 0.3	V
T_{stg}	Storage temperature range		–65	150	°C
T_J	Junction temperature			150	°C
	Bump temperature (soldering)	Infrared (15 s)		220	°C
		Vapor phase (60 s)		215	
	Lead temperature (soldering, 10 s)			300	°C

(1) Stresses beyond those listed under Absolute Maximum Ratings may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

Electrical Characteristics

V_{CC} = 5 V ± 10%, T_A = -40°c to 85°C (unless otherwise noted)

PARAMETER		TEST CONDITIONS		MIN	TYP(1)	MAX	UNIT
V_{CC}	Supply voltage			0.9		5.5	V
I_{CC}	Supply current				1	100	nA
V_F	Diode forward voltage	I_F = 10 mA		0.65		0.95	V
VBR	Breakdown Voltage	I_{BR} = 10mA		11			V
V_C	Channel clamp voltage(2)	T_A = 25°C, ±15-kV HBM, I_F = 10 A	Positive transients			V_{CC} + 25	V
			Negative transients			–25	
		T_A = 25°C, ±8-kV Contact Discharge (IEC 61000-4-2), I_F = 24 A	Positive transients			V_{CC} + 60	
			Negative transients			–60	
		T_A = 25°C, ±15-kV Air-Gap Discharge (IEC 61000-4-2), I_F = 45 A	Positive transients			V_{CC} + 100	
			Negative transients			–100	
$I_{i/o}$	Channel leakage current	$V_{i/o}$ = GND or V_{CC}				±1	nA
C_{io}	Channel input capacitance	V_{CC} = 5 V, bias of V_{CC}/2			1.5		pF

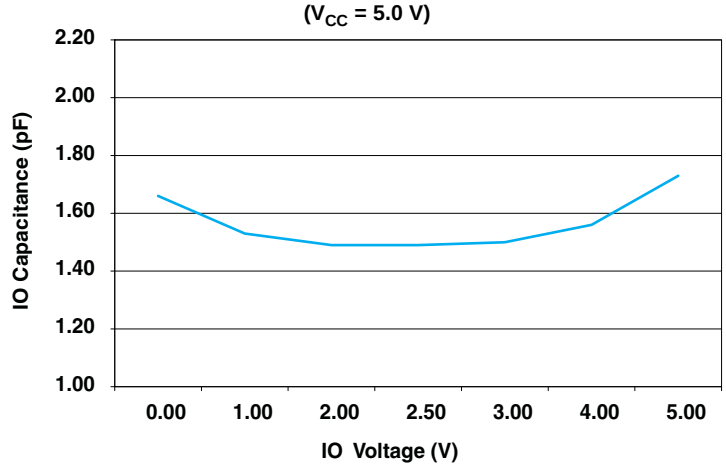
(1) Typical values are at V_{CC} = 5 V and T_A = 25°C.
(2) Channel clamp voltage is not production tested.

ESD Protection

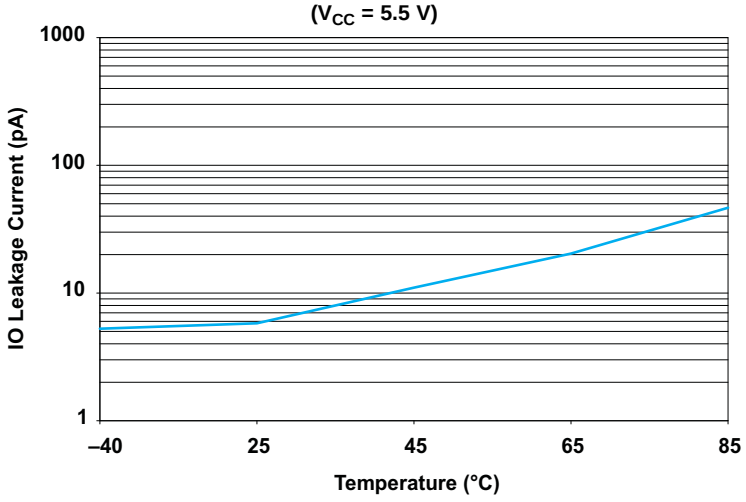
PARAMETER	TYP	UNIT
HBM	±15	kV
IEC 61000-4-2 Contact Discharge	±8	kV
IEC 61000-4-2 Air-Gap Discharge	±15	kV

TYPICAL OPERATING CHARACTERISTICS

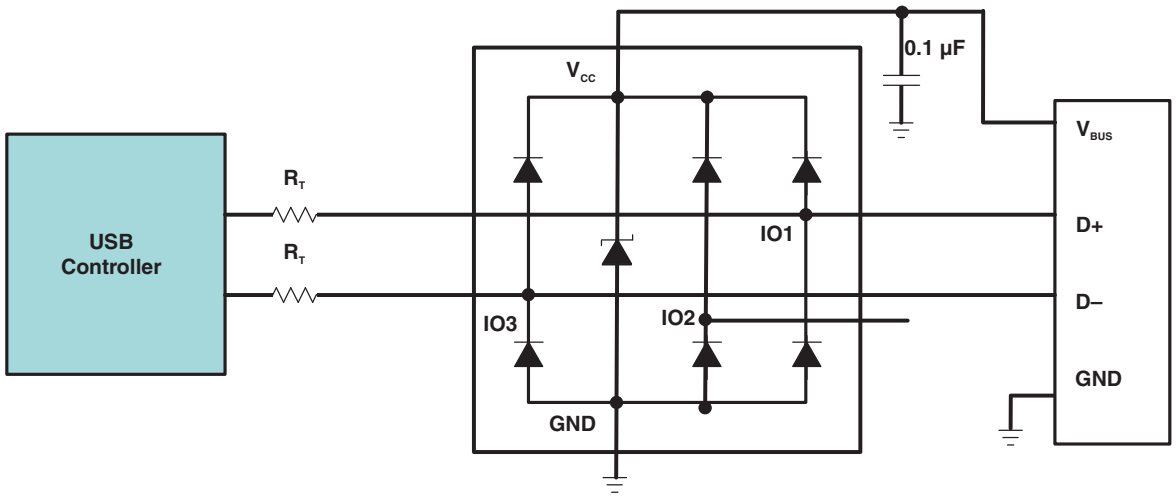
IO CAPACITANCE
vs
IO VOLTAGE
(V_{CC} = 5.0 V)



IO LEAKAGE CURRENT
vs
TEMPERATURE
(V_{CC} = 5.5 V)



APPLICATION INFORMATION



Detailed Description

When placed near the connector, the TPD3E001 ESD solution offers little or no signal distortion during normal operation due to low IO capacitance and ultra-low leakage current specifications. The TPD3E001 ensures that the core circuitry is protected and the system is functioning properly in the event of an ESD strike. For proper operation, the following layout/ design guidelines should be followed:

1. Place the TPD3E001 solution close to the connector. This allows the TPD3E001 to take away the energy associated with ESD strike before it reaches the internal circuitry of the system board.
2. Place a 0.1-µF capacitor very close to the V_{CC} pin. This limits any momentary voltage surge at the IO pin during the ESD strike event.
3. Ensure that there is enough metallization for the V_{CC} and GND loop. During normal operation, the TPD3E001 consumes nA leakage current. But during the ESD event, V_{CC} and GND may see 15 A to 30 A of current, depending on the ESD level. Sufficient current path enables safe discharge of all the energy associated with the ESD strike.
4. Leave the unused IO pins floating.
5. The V_{CC} pin can be connected in two different ways:

a. If the V_{CC} pin is connected to the system power supply, the TPD3E001 works as a transient suppressor for any signal swing above V_{CC} + V_F. A 0.1-µF capacitor on the device V_{CC} pin is recommended for ESD bypass.

b. If the V_{CC} pin is not connected to the system power supply, the TPD3E001 can tolerate higher signal swing in the range up to 10 V. Please note that a 0.1-µF capacitor is still recommended at the V_{CC} pin for ESD bypass.

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)	Op Temp (°C)	Top-Side Markings (4)	Samples
TPD3E001DRLR	ACTIVE	SOT	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	2BR	Samples
TPD3E001DRLRG4	ACTIVE	SOT	DRL	5	4000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	2BR	Samples
TPD3E001DRSR	ACTIVE	SON	DRS	6	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 85	ZWL	Samples
TPD3E001DRYR	ACTIVE	SON	DRY	6	5000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	2B	Samples
TPD3E001DRYRG4	ACTIVE	SON	DRY	6	5000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM	-40 to 85	2B	Samples

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

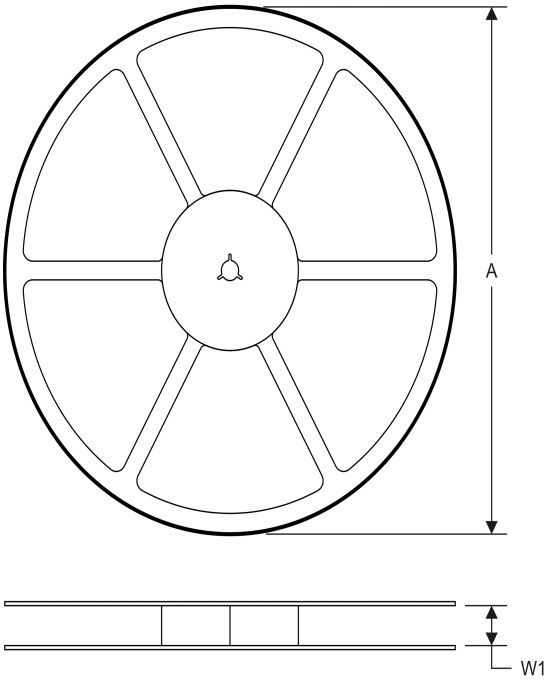
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) Only one of markings shown within the brackets will appear on the physical device.

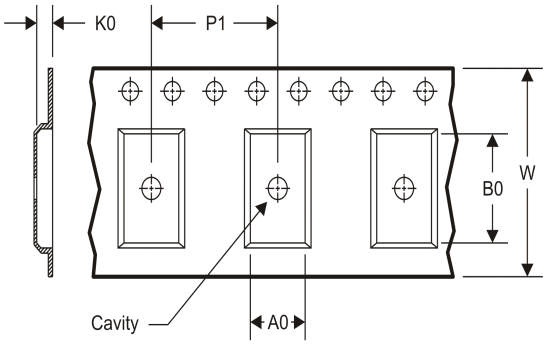
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



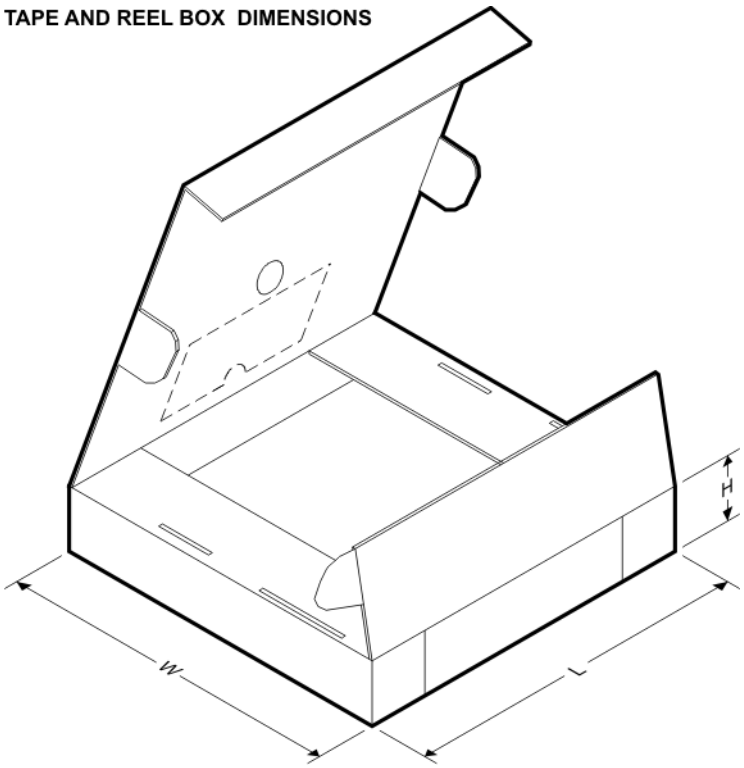
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

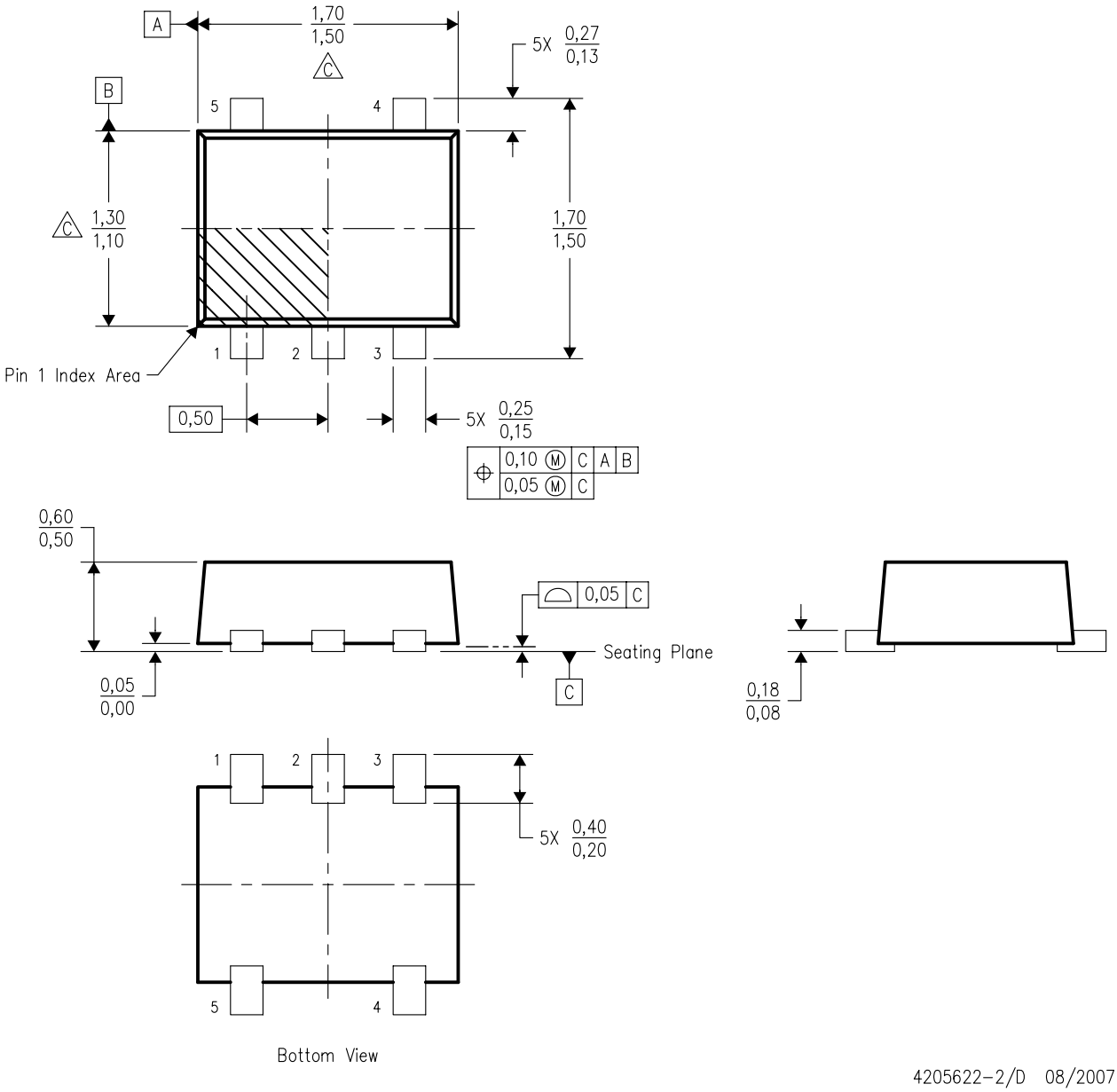
Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
TPD3E001DRLR	SOT	DRL	5	4000	180.0	8.4	1.98	1.78	0.69	4.0	8.0	Q3
TPD3E001DRSR	SON	DRS	6	1000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
TPD3E001DRYR	SON	DRY	6	5000	179.0	8.4	1.2	1.65	0.7	4.0	8.0	Q1

TAPE AND REEL BOX DIMENSIONS



*All dimensions are nominal

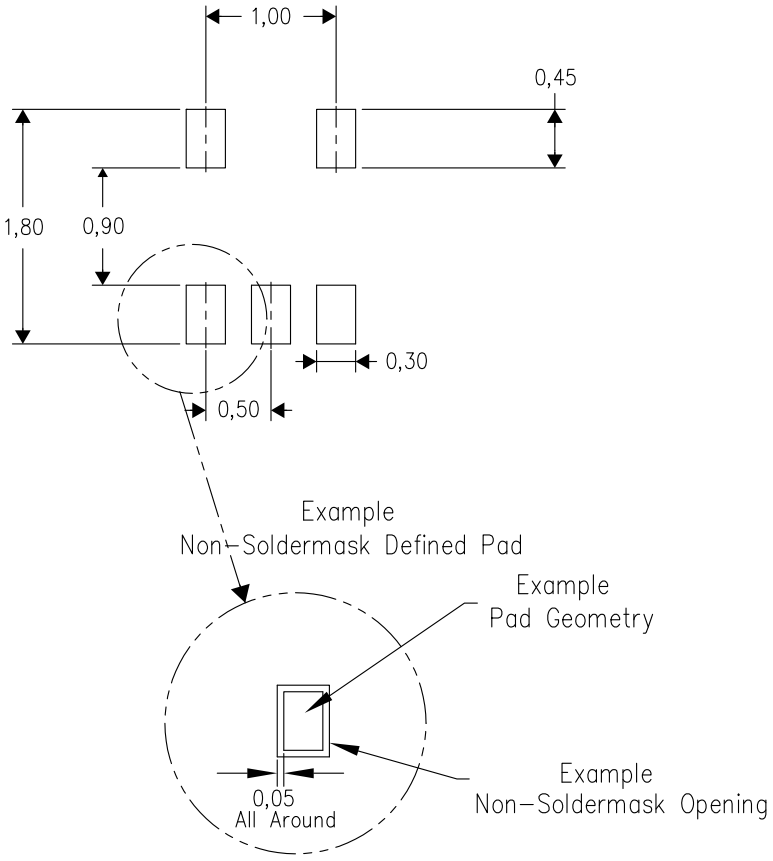
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
TPD3E001DRLR	SOT	DRL	5	4000	202.0	201.0	28.0
TPD3E001DRSR	SON	DRS	6	1000	367.0	367.0	35.0
TPD3E001DRYR	SON	DRY	6	5000	203.0	203.0	35.0



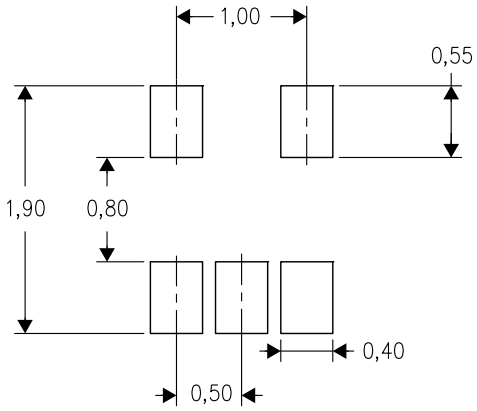
NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash, interlead flash, protrusions, or gate burrs. Mold flash, interlead flash, protrusions, or gate burrs shall not exceed 0,15 per end or side.
D. JEDEC package registration is pending.

DRL (R–PDSO–N5) PLASTIC SMALL OUTLINE

Example Board Layout



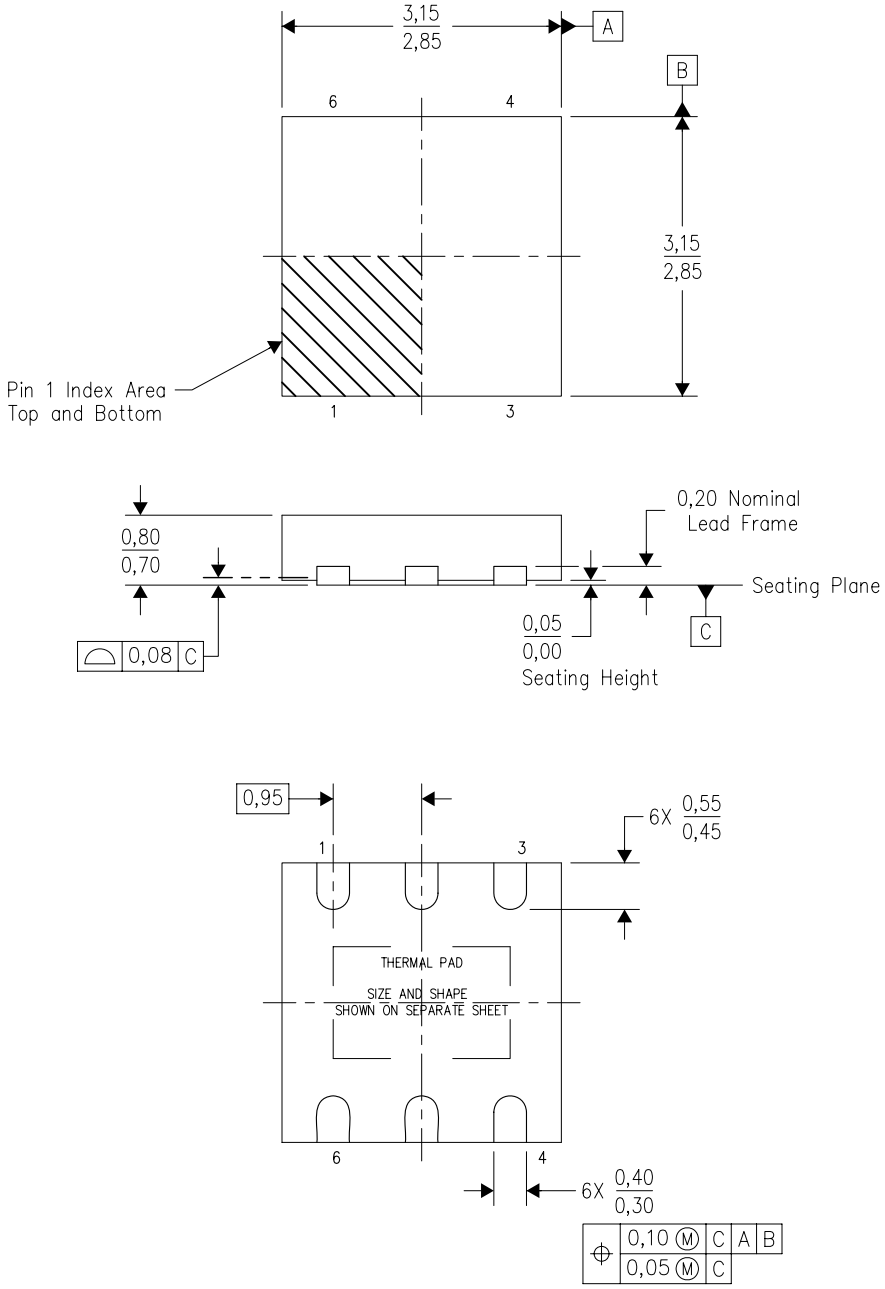
Example Stencil Design
(Note E)



4208207–2/E 06/12

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
E. Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
G. Side aperture dimensions over–print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

DRS (S–PWSON–N6) PLASTIC SMALL OUTLINE NO–LEAD



4206219/F 07/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. SON (Small Outline No–Lead) package configuration.
D. The package thermal pad must be soldered to the board for thermal and mechanical performance.
E. See the additional figure in the Product Data Sheet for details regarding the exposed thermal pad features and dimensions.

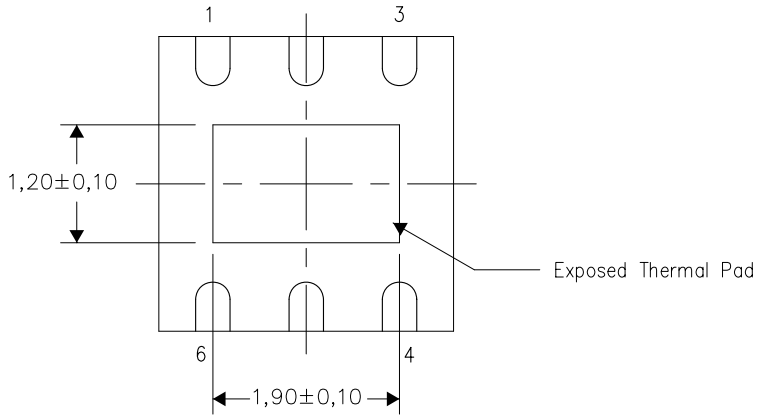
DRS (S–PWSON–N6) PLASTIC SMALL OUTLINE NO–LEAD

THERMAL INFORMATION

This package incorporates an exposed thermal pad that is designed to be attached directly to an external heatsink. The thermal pad must be soldered directly to the printed circuit board (PCB). After soldering, the PCB can be used as a heatsink. In addition, through the use of thermal vias, the thermal pad can be attached directly to the appropriate copper plane shown in the electrical schematic for the device, or alternatively, can be attached to a special heatsink structure designed into the PCB. This design optimizes the heat transfer from the integrated circuit (IC).

For information on the Quad Flatpack No–Lead (QFN) package and its advantages, refer to Application Report, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271. This document is available at www.ti.com.

The exposed thermal pad dimensions for this package are shown in the following illustration.



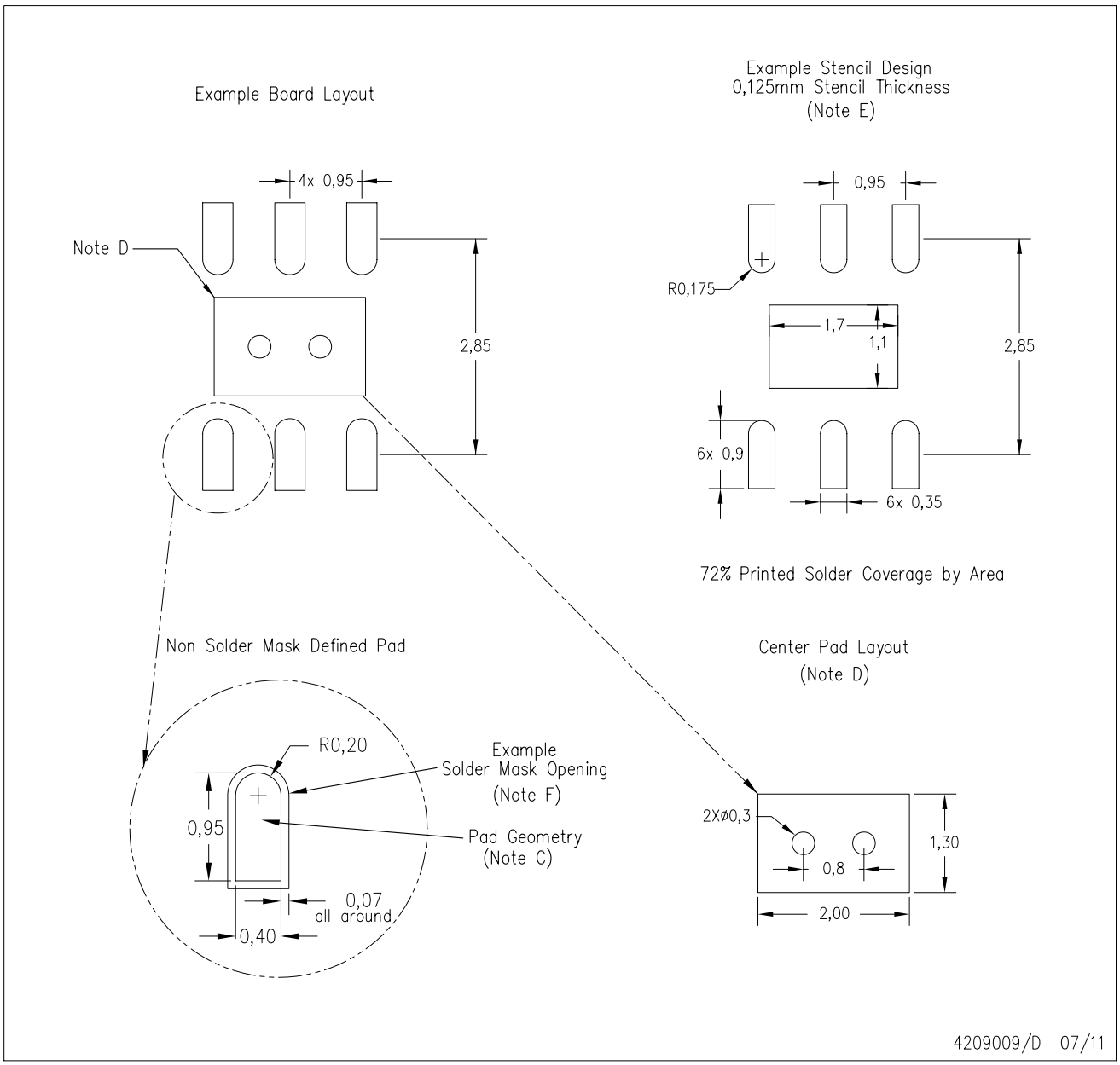
Bottom View

Exposed Thermal Pad Dimensions

4207663/E 07/11

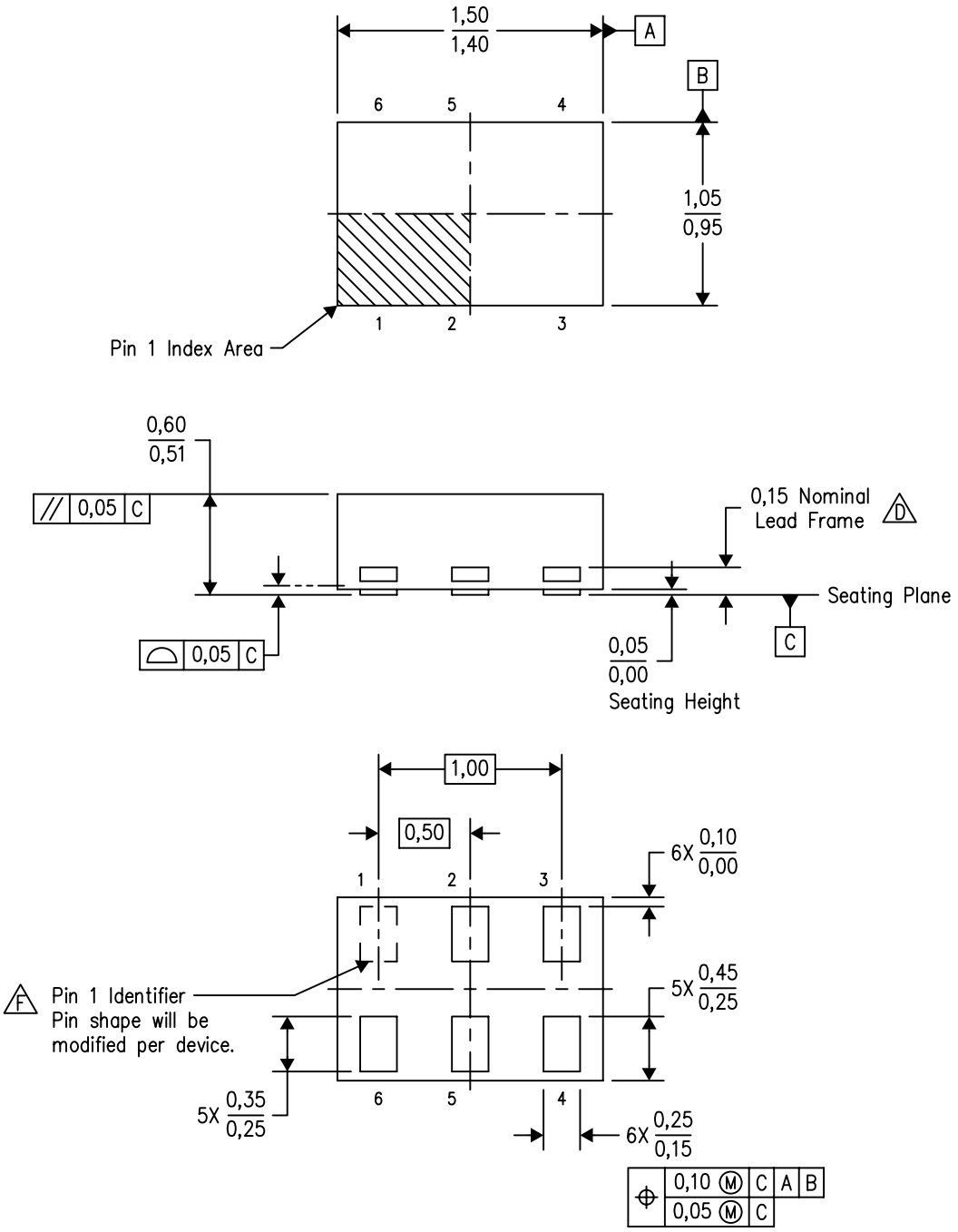
NOTE: All linear dimensions are in millimeters

DRS (S–PWSON–N6) PLASTIC SMALL OUTLINE NO–LEAD



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. This package is designed to be soldered to a thermal pad on the board. Refer to Application Note, QFN/SON PCB Attachment, Texas Instruments Literature No. SLUA271, and also the Product Data Sheets for specific thermal information, via requirements, and recommended board layout. These documents are available at www.ti.com <http://www.ti.com>.
E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
F. Customers should contact their board fabrication site for solder mask tolerances.

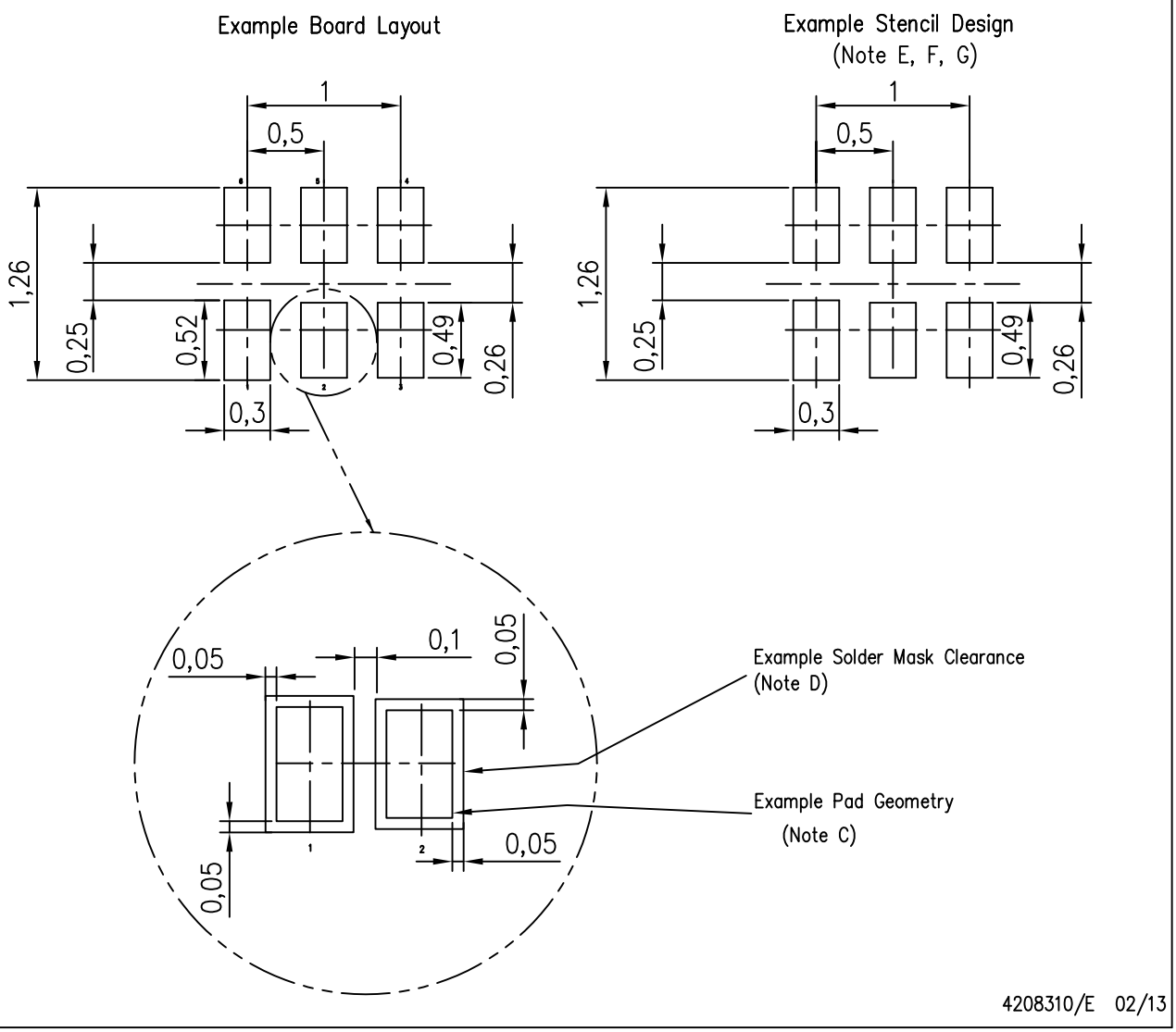
DRY (R–PUSON–N6) PLASTIC SMALL OUTLINE NO–LEAD



4207181/F 12/11

NOTES:
A. All linear dimensions are in millimeters. Dimensioning and tolerancing per ASME Y14.5M–1994.
B. This drawing is subject to change without notice.
C. SON (Small Outline No–Lead) package configuration.
D. The exposed lead frame feature on side of package may or may not be present due to alternative lead frame designs.
E. This package complies to JEDEC MO–287 variation UFAD.
F. See the additional figure in the Product Data Sheet for details regarding the pin 1 identifier shape.

DRY (R–PUSON–N6) PLASTIC SMALL OUTLINE NO–LEAD



NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Customers should contact their board fabrication site for minimum solder mask web tolerances between signal pads.
E. Maximum stencil thickness 0,127 mm (5 mils). All linear dimensions are in millimeters.
F. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC 7525 for stencil design considerations.
G. Side aperture dimensions over–print land for acceptable area ratio > 0.66. Customer may reduce side aperture dimensions if stencil manufacturing process allows for sufficient release at smaller opening.

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Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components as meeting ISO/TS16949 requirements, mainly for automotive use. In any case of use of non-designated products, TI will not be responsible for any failure to meet ISO/TS16949.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
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Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
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